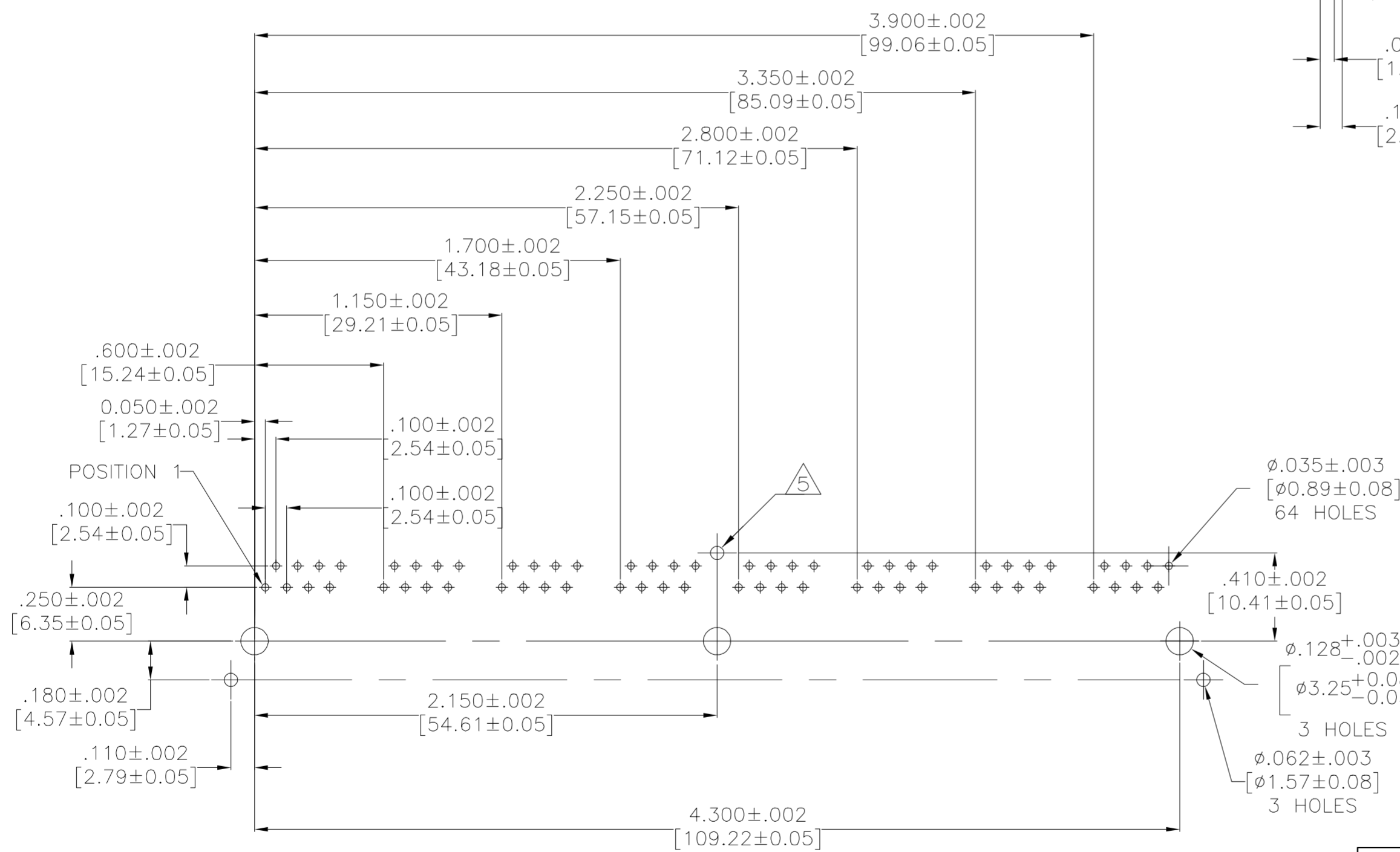
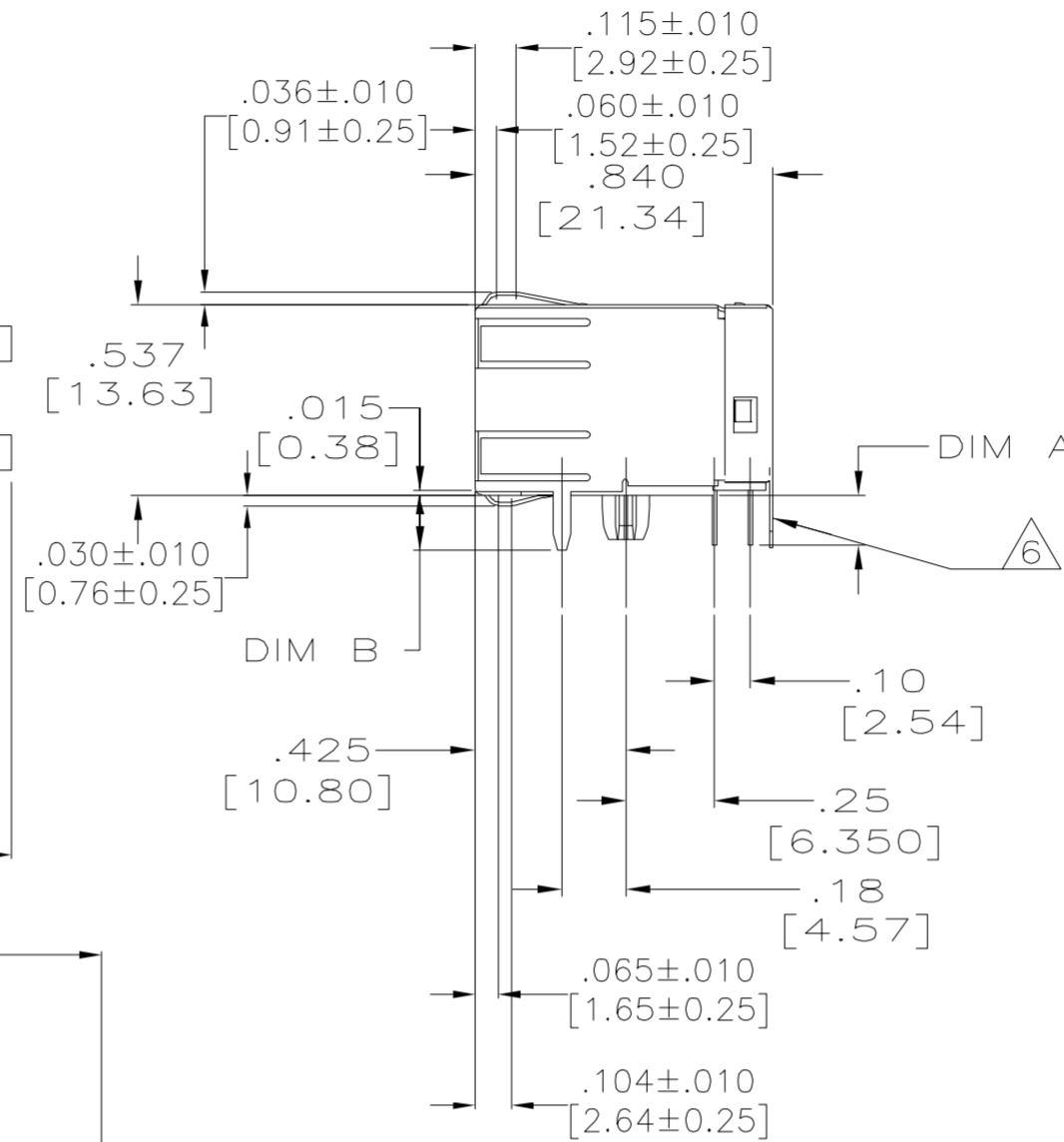
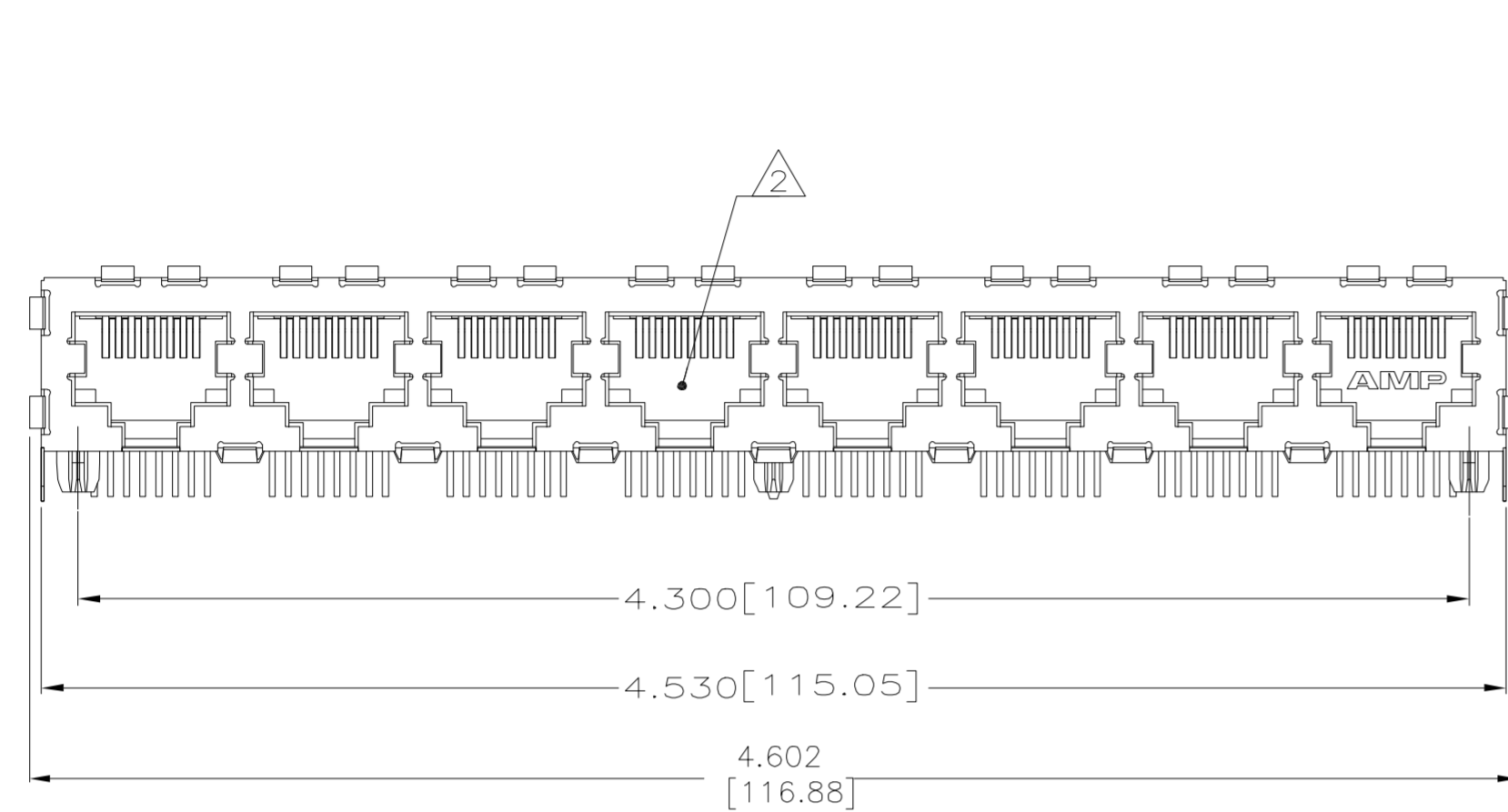


REVISIONS					
P	LTR	DESCRIPTION	DATE	DWN	APVD
F7		ECR-19-014657	13DEC2020	RR	SZ



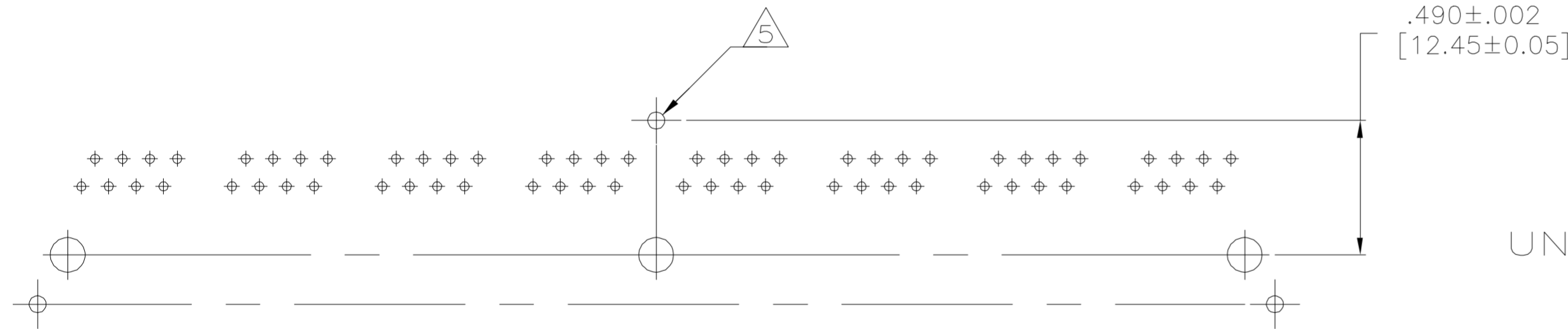
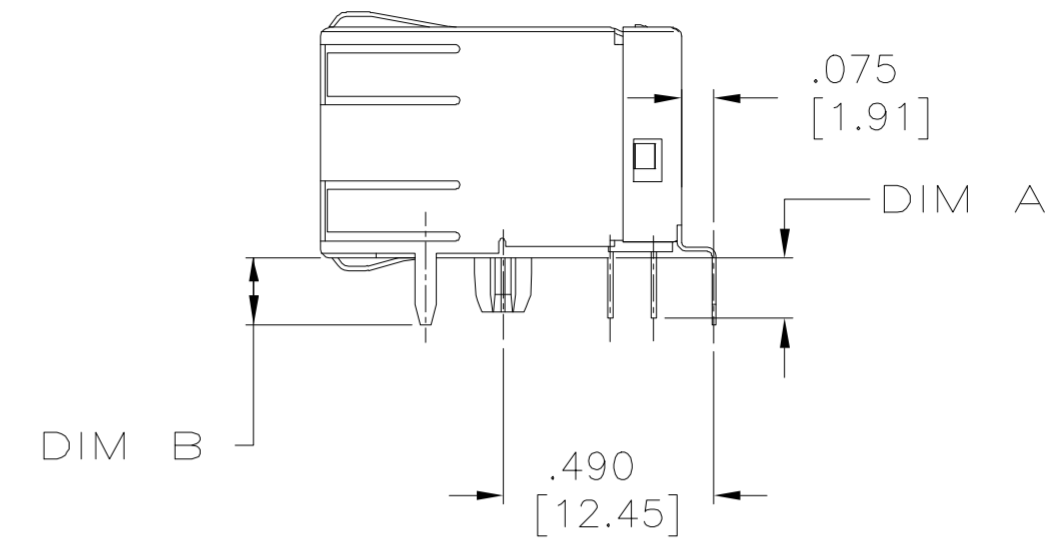
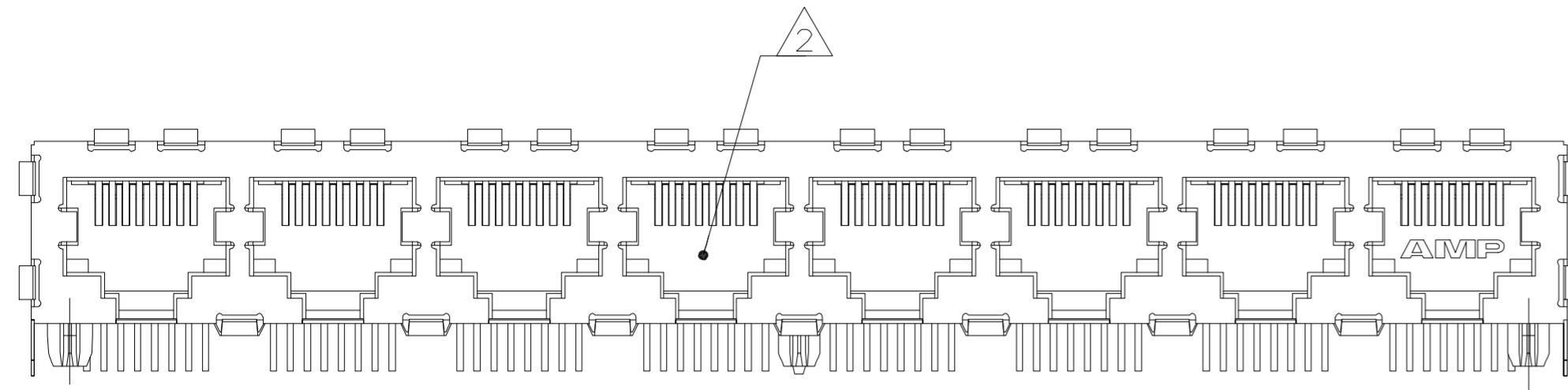
- △ MATERIAL:  
HOUSING - NYLON, COLOR: BLACK, UL94V-0.  
OVERMOLDED TERMINAL ARRAY - HTN, BROWN.  
TERMINALS-.013 [0.33] THICK PHOS BRONZE  
PLATED WITH .000050 [1.27µm] THICK HARD  
GOLD IN LOCALIZED AREA AND .000150 [3.81 µm] MIN  
THICK MATTE TIN IN SOLDER AREA OVER .000050  
[1.27 µm] MIN THICK NICKEL UNDERPLATE  
SHIELDS - .010 [0.254] THICK COPPER ALLOY  
PLATED WITH 1.27 µm [0.00050] MINIMUM NICKEL  
AND 2.03 µm [0.00080] MINIMUM HOT TIN DIP ON  
PCB GROUND TABS.
- △ JACK CAVITY CONFORMS TO FCC RULES AND  
REGULATIONS, PART 68 SUBPART F.
- 3. ALL DIMENSIONS SHOWN ARE NOMINAL UNLESS  
OTHERWISE SPECIFIED.
- 4. ALL DIMENSIONS SHOWN IN BRACKETS [ ] ARE  
IN MILLIMETERS.
- △ THIS HOLE IS NEEDED FOR -1 AND -3 ONLY.
- △ THIS TAB REMOVED ON -2.
- △ THE PART IS PRELIMINARY
- △ MATERIAL:  
HOUSING - NYLON, COLOR: BLACK, UL94V-0.  
OVERMOLDED TERMINAL ARRAY - PBT, BROWN.  
TERMINALS-.013 [0.33] THICK PHOS BRONZE  
PLATED WITH .000050 [1.27µm] THICK HARD  
GOLD IN LOCALIZED AREA AND .000150 [3.81 µm] MIN  
THICK MATTE TIN IN SOLDER AREA OVER .000050  
[1.27 µm] MIN THICK NICKEL UNDERPLATE  
SHIELDS - .010 [0.254] THICK COPPER ALLOY  
PLATED WITH 1.27 µm [0.00050] MINIMUM NICKEL  
AND 2.03 µm [0.00080] MINIMUM HOT TIN DIP ON  
PCB GROUND TABS.
- △ OBSOLETE PARTS: OBSOLETE CIS STREAMLINING  
PER D.RENAUD/D.SINISI

△	.128±.010	.128±.010	WITH REAR PC BOARD GROUND TAB	5406491-5
△	.128±.010	.128±.010	WITH REAR PC BOARD GROUND TAB	5406491-4
△	.155	.140±.015	WITHOUT REAR PC BOARD GROUND TAB	5406491-2
△	.155	.140±.015	WITH REAR PC BOARD GROUND TAB	5406491-1
MATERIAL	DIM B (INCHES)	DIM A (INCHES)	DESCRIPTION	PART NO.

FOR P/N:5406491-1&-2  
SUGGESTED PC BOARD LAYOUT  
COMPONENT SIDE  
SEE APPLICATION SPECIFICATION

THIS DRAWING IS A CONTROLLED DOCUMENT.		DWN	13DEC2020	TE Connectivity	
		CHK	14APR2009		
		APVD	14APR2009	NAME	
		Denny Zhu		Denny Zhu	
		Steven Yao		STE	
		108-1163-2		MODULAR JACK, PANEL GROUND, 8P, RIGHT ANGLE SHIELDED, CAT 5e	
		114-2048		-	
		0		-	
		A2		-	
		00779		-	
		C=5406491		-	
		1:1		-	
		1 of 2		-	
		F7		-	

REVISIONS					
P	LTR	DESCRIPTION	DATE	DWN	APVD
-	-	SEE SHEET 1	-	-	-



FOR P/N:5406491-4;-5  
SUGGESTED PC BOARD LAYOUT  
 COMPONENT SIDE  
 SEE APPLICATION SPECIFICATION

UNMARKED DIMENSIONS SAME AS P/N:5406491-1

THIS DRAWING IS A CONTROLLED DOCUMENT.		DWN	13DEC2020		<b>TE</b> TE Connectivity
DIMENSIONS: mm		CHK	-		
TOLERANCES UNLESS OTHERWISE SPECIFIED:		APVD	-		NAME
0 PLC ± -		PRODUCT SPEC	-		MODULAR JACK, PANEL GROUND, 8P, RIGHT ANGLE
1 PLC ± -		APPLICATION SPEC	-		SHEILED, CAT 5e
2 PLC ± -		WEIGHT	-		SIZE
3 PLC ± -		CUSTOMER DRAWING	-		A2
4 PLC ± -		SCALE	1:1		CAGE CODE
ANGLES ± -		SHEET	2 of 2		00779
FINISH		REV	F7		DRAWING NO
MATERIAL		RESTRICTED TO	-		C=5406491